SHEET 1 OF 2 SERIAL NO. ATTY. DOCKET NO. 09/998,384 005916 USA/ INFORMATION DISCLOSURE FPS/MMCS/MC CITATION IN AN APPLICATION (PTO-1449) APPLICANT Young Joseph PAIK FILING DATE **GROUP** 2812 2823 November 30, 2001 U.S. PATENT DOCUMENTS **EXAMINER'S** FILING INITIALS CLASS SUBCLASS PATENT NO. DATE NAME DATE 6,381,564 B1 04/30/02 David et al. 05/03/99 703 Kr. 2002/0183986 A1 12/05/02 Stewart et al. 05/30/01 2 K.N. 2003/0154062 A1 08/14/03 Daft et al. 10/15/01 KN. 6,529,789 B1 03/04/03 Campbell et al. 03/14/02 700 115 K.N. 08/10/04 6,774,998 B1 Wright et al. 12/27/01 401 K.N. 6,751,518 B1 06/15/04 Sonderman et al. 04/29/02 700 121 KN 6,678,570 B1 01/13/04 06/26/01 Pasadyn et al. 700 109 KN 6,735,492 B2 05/11/04 Conrad et al. 07/19/02 KN. 700 121 **EXAMINER** DATE CONSIDERED

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Young Joseph PAIK

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ATTY. DOCKET NO. 005916 USA/ FPS/MMCS/MC

SERIAL NO. 09/998,384

APPLICANT

Young Joseph PAIK

FILING DATE November 30, 2001

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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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SHEET 4 OF 11 SERIAL NO. ATTY, DOCKET NO. 005916 09/998.384 INFORMATION DISCLOSURE USA/FPS/MMCS/MC CITATION IN AN **APPLICATION** (PTO-1449) APPLICANT Young Joseph PAIK FILING DATE GROUP November 30, 2001 2812 2823 U.S. PATENT DOCUMENTS EXAMINER'S FILING INITIALS PATENT NO. DATE NAME CLASS SUBCLASS DATE 2001/0042690 11/22/01 Talieh 12/14/00 и8 205 6,324,481 11/27/01 Atchison et al. 06/15/99 6,334,807 01/01/02 Lebel et al. 451 04/30/99 6.336.841 01/08/02 Chang 03/29/01 451 2002/0032499 03/14/02 Wilson et al. 05/04/01 159 7 6,360,133 03/19/02 Campbell et al. 06/17/99 700 6,360,184 03/19/02 Jacquez 03/26/97 202 181 6,368,883 04/09/02 Bode et al. 08/10/99 438 6,368,884 04/09/02 Goodwin et al. 04/13/00 438 6,379,980 04/30/02 Toprac 07/26/00 428 6,388,253 05/14/02 Su 11/02/00 250 2002/0058460 05/16/02 Lee et al. 09/14/01 451 6,395,152 05/28/02 Wang 07/02/99 ZOY 6,397,114 05/28/02 Eryurek et al. 05/03/99 51 6,405,096 06/11/02 Toprac et al. 08/10/99 200 6,405,144 06/11/02 Toprac et al. 01/18/00 702 84 2002/0070126 06/13/02 Sato et al. 09/19/01 640 2002/0081951 06/27/02 Boyd et al. 02/20/02 451 56 2002/0089676 07/11/02 Pecen et al. 04/26/00 2002/0102853 08/01/02 Li et al. 12/20/01 692 2002/0107599 08/08/02 Patel et al. 01/25/01 200 6,435,952 08/20/02 Boyd et al. 451 06/30/00 6,438,438 08/20/02 Takagi et al. 01/02/98 700 2002/0113039 08/22/02 Mok et al. 02/16/01 9 6,440,295 08/27/02 Wang 02/04/00 ક ૫૦ 2002/0127950 09/12/02 Hirose et al. 03/08/01 6,455,937 09/24/02 03/17/99 Cunningham EXAMINER **DATE CONSIDERED** 

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SHEET 2 OF 4 SERIAL NO. ATTY, DOCKET NO. 09/998.384 5916/FET/FET/DV INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449) APPLICANT Young Joseph PAIK FILING DATE GROUP' November 30, 2001 U.S. PATENT DOCUMENTS FILING DATE INITIALS PATENT NO. DATE NAME CLASS SUBCLASS 10/25/96 5,859,964 01/12/99 Wang et al. K.W. 5,863,807 01/26/99 Jang et al. 03/15/96 5,870,306 02/09/99 Harada 06/13/97 5.903.455 05/11/99 Sharpe, Jr. et al. 12/12/96 188 06/29/99 5,916,016 Bothra 10/23/97 298 5,923,553 07/13/99 Yi 10/05/96 5,930,138 07/27/99 Lin et al. 09/10/97 468.15 5,940,300 08/17/99 Ozaki 05/08/97 G68.28 5,960,214 09/28/99 Sharpe, Jr. et al. 12/04/96 395 835 5,963,881 10/05/99 Kahn et al. 10/20/97 35 5,982,920 11/09/99 Tobin, Jr. et al. 01/08/97 382 145 6,041,270 03/21/00 Steffan et al. 12/05/97 21 700 6,078,845 06/20/00 Friedman 11/25/96 MY 200 6,112,130 08/29/00 Fukuda et al. 10/01/97 700 121 6.148.246 11/14/00 Kawazome 06/10/98 200 FOREIGN PATENT DOCUMENTS **EXAMINER'S** PATENT NO. DATE COUNTRY SUBCLASS INITIALS No 0747795A2 12/11/96 Енгоре X 10-173029 06/26/98 X Japan 0 895 145 A1 02/03/99 Europe X 11-126816 05/11/99 Japan OTHER ART (Including Author, Title, Date, Pertinent, Pages, Etc.) Schmid, Hans Albrecht. 1995. "Creating the Architecture of a Manufacturing Framework by Design K.N. Patterns." Austin, Texas: OOPSLA. Baliga, John. July 1999. "Advanced Process Control: Soon to be a Must." Cahners Semiconductor KN. International. www.semiconductor.net/semiconductor/issues/issues/1999/jul99/docs/feature1.asp **EXAMINER** 

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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	6,185,324	02/06/01	Ishihara et al.		382		01/31/9	)5
	6,192,291	02/20/01	Kwon	, .	700	151	10/08/9	)8
	6,197,604	03/06/01	Miller et al.		438		10/01/9	)8
	6,211,094	04/03/01	Jun et al.		438		08/23/9	99
	6,226,792	05/01/01	Goiffon et al.	<del></del>	717	11	10/14/9	98
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	6,252,412	06/26/01	Talbot et al.		324	750	01/08/	
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	6,303,395	10/16/01	Nulman		438	52	06/01/	99
	6,345,315	02/05/02	Mishra		709	3 29	08/12/	
¥.~	6,366,934	04/02/02	Cheng et al.		207	513	06/02/	99
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K.N.	4,796,194	01/03/89	Atherton		364	468	08/20/86
	5,089,970	02/18/92	Lee et al.		364	468	10/05/89
	5,108,570	04/28/92	Wang	Wang		1923	03/30/90
	5,220,517	06/15/93	Sierk et al.	Sierk et al.		550	08/31/90
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	5,329,463	07/12/94	Sierk et al.		356	510	01/13/93
	5,367,624	11/22/94	Cooper		395	T	06/11/93
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K.N.	5,490,097	02/06/96	Swenson et al.		364	578	08/06/	93
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	5,657,254	08/12/97	Sierk et al.		364		04/15/	'96
	5,661,669	08/26/97	Mozumder et al.		364	552	06/07/	95
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<u> </u>	5,698,989	12/16/97	Nulman		324	719	09/13/	
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K.N.	2,165,847	08/29/91	Canada				x	
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	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes				1
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SHEET 1 OF 1 ATTY. DOCKET NO. SERIAL NO. 09/998,384 5916/FET/FET/DV INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449) APPLICANT Young Joseph PAIK FILING DATE GROUP 2823 November 30, 2001 2812 U.S. PATENT DOCUMENTS ·,;: **EXAMINER'S** PATENT FILING INITIALS APPLICATION DATE NAME TITLE CLASS SUB-NO. CLASS FOREIGN PATENT DOCUMENTS EXAMINER'S PATENT NO. INITIALS DATE COUNTRY CLASS SUB-Translation CLASS Yes No OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) Consilium. January 1999. "FAB300™: Consilium's Next Generation MES Solution of Software and Services K,N. which Control and Automate Real-Time FAB Operations." www.consilium.com/products/fab300\_page.htm#FAB300 Introduction Consilium. July 1999. "Increasing Overall Equipment Effectiveness (OEE) in Fab Manufacturing by Implementing Consilium's Next-Generation Manufacturing Execution System - MES II." Semiconductor Fabtech Edition 10. Consilium Corporate Brochure. October 1999. www.consilium.com Moyne, James. October 1999. "Advancements in CMP Process Automation and Control." Hawaii: (Invited paper and presentation to) Third International Symposium on Chemical Mechanical Polishing in IC Device Manufacturing: 196th Meeting of the Electrochemical Society. Consilium. November 1999. FAB300™ Update. SEMI. 2000. "Provisional Specification for CIM Framework Scheduling Component." San Jose, California. Lee, Brian, Duane S. Boning, Winthrop Baylies, Noel Poduje, Pat Hester, Yong Xia, John Valley, Chris Koliopoulus, Dale Hetherington, HongJiang Sun, and Michael Lacy. April 2001. "Wafer Nanotopography Effects on CMP: Experimental Validation of Modeling Methods." San Francisco, California: Materials Research Society Spring Meeting. NovaScan 2020. February 2002. "Superior Integrated Process Control for Emerging CMP High-End K.N. Applications." **EXAMINER DATE CONSIDERED** 

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